





40V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = 25°C
40)/	8.5mΩ @ V _{GS} = 10V	27.6A
40V	14mΩ @ V _{GS} = 4.5V	21.5A

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- DC-DC Converters
- Power management functions

Features and Benefits

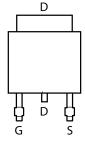
- Low on-resistance
- Fast switching speed
- "Green" component and RoHS compliant (Note 1)

Mechanical Data

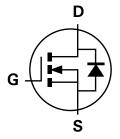
- Case: TO252-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Below Ordering Information: See Below Weight: 0.33 grams (approximate)



TOP VIEW



PIN OUT -TOP VIEW



Equivalent Circuit

Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN4009LK3-13	N4009L	13	16	2,500

Note:

1. Diodes, Inc. defines "Green" products as those which are Eu RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information



⊃;; = Manufacturer's Marking N4009L = Product Type Marking Code YYWW = Date Code Marking YY = Last two digits of year (ex: 09 = 2009) WW = Week (01-52)





Maximum Ratings @T_A = 25°C unless otherwise specified

Cha	racteristic		Symbol Value		Unit	
Drain-Source voltage			V_{DSS}	40	V	
Gate-Source voltage			V_{GS}	±20	V	
		(Note 3)	ID	27.6		
Continuous Drain current	$V_{GS} = 10V$	T _A =70°C (Note 3)		22.1	Α	
		(Note 2)		18.0		
Pulsed Drain current	V _{GS} = 10V	(Note 4)	I _{DM}	96.6	Α	
Continuous Source current (Body diode) (Note 3)		I _S	13.2	Α		
Pulsed Source current (Body diode) (Note 4)		I _{SM}	96.6	A		

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
	(Note 2)		4.36 34.8	
Power dissipation Linear derating factor	(Note 3)	P _D	P _D 10.3 82.4	
	(Note 5)		2.19 17.5	
Thermal Resistance, Junction to Ambient	(Note 2) (Note 3) (Note 5)	$R_{ hetaJA}$	28.6 12.1 57.0	°C/W
Thermal Resistance, Junction to Lead	(Note 6)	$R_{ heta JL}$	0.85	
Operating and storage temperature range		T _J , T _{STG}	-55 to 150	°C

Notes:

- 2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

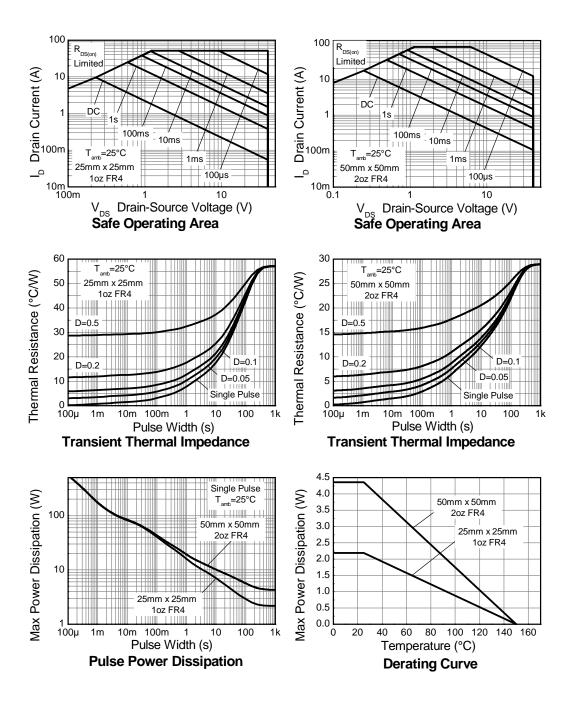
- 3. Same as note 2, except the device is measured at t ≤ 10 sec.

 4. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.

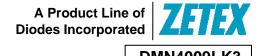
 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 6. Thermal resistance from junction to solder-point (at the end of the drain lead).



Thermal Characteristics







DMN4009LK3

Electrical Characteristics @TA = 25°C unless otherwise specified

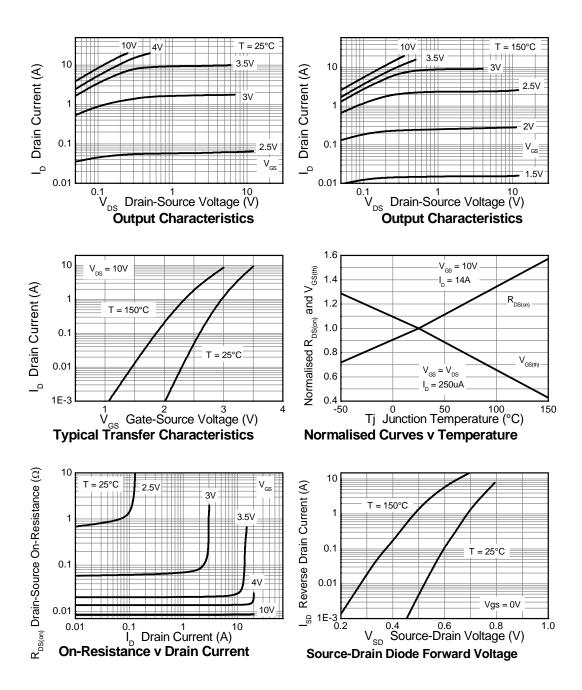
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS						•		
Drain-Source Breakdown Voltage	BV _{DSS}	40	_		V	$I_D = 250 \mu A, V_{GS} = 0 V$		
Zero Gate Voltage Drain Current	I _{DSS}	_	_	0.5	μА	V _{DS} = 40V, V _{GS} = 0V		
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	V _{GS} = ±20V, V _{DS} = 0V		
ON CHARACTERISTICS								
Gate Threshold Voltage	V _{GS(th)}	1.0		3.0	٧	I_D = 250 μ A, V_{DS} = V_{GS}		
Static Drain-Source On-Resistance (Note 7)	В			8.5	mΩ	V _{GS} = 10V, I _D = 14A		
Static Dialif-Source Off-Resistance (Note 1)	R _{DS (ON)}	_	_	14	11177	DS= 40V, V _{GS} = 0V DS= 40V, V _{DS} = 0V DS= ±20V, V _{DS} = 0V DS= ±20V, V _{DS} = 0V DS= 10V, I _D = 14A DS= 15V, I _D = 11A DS= 15V, I _D = 12A DS= 14A, V _{GS} = 0V DS= 20V, V _{GS} = 0V DS= 20V, V _{GS} = 0V DS= 20V		
Forward Transconductance (Notes 7 & 8)	g fs	_	35.3		S	V _{DS} = 15V, I _D = 12A		
Diode Forward Voltage (Note 7)	V _{SD}	_	0.82	1.0	V	I _S = 14A, V _{GS} = 0V		
Reverse recovery time (Note 8)	t _{rr}		141	_	ns	1 14A di/dt 100A/		
Reverse recovery charge (Note 8)	Q _{rr}	_	872	_	nC	-I _S = 14A, di/dt= 100A/μs		
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	C _{iss}	_	2072		pF			
Output Capacitance	Coss	_	338	_	pF	,		
Reverse Transfer Capacitance	C _{rss}	_	193	_	pF	11 11VII 12		
Total Gate Charge	Q_g	_	21		nC	V _{GS} = 4.5V		
Total Gate Charge	Q_g	_	42	_	nC	V _{DS} = 20V		
Gate-Source Charge	Q_{gs}	_	7.3	_	nC	V _{GS} = 10V I _D = 14A		
Gate-Drain Charge	Q_{gd}	_	10.7	_	nC			
Turn-On Delay Time (Note 9)	t _{D(on)}	_	7.8	_	ns			
Turn-On Rise Time (Note 9)	t _r	_	18.5	_	ns	V _{DD} = 20V, V _{GS} = 10V		
Turn-Off Delay Time (Note 9)	t _{D(off)}	_	37.3	_	ns	I_D = 14A, $R_G \cong 6.0\Omega$		
Turn-Off Fall Time (Note 9)	t _f	_	14.9		ns			

Notes:

- 7. Measured under pulsed conditions. Pulse width $\leq 300 \mu s;$ duty cycle $\leq 2\%$
- For design aid only, not subject to production testing.
 Switching characteristics are independent of operating junction temperatures.

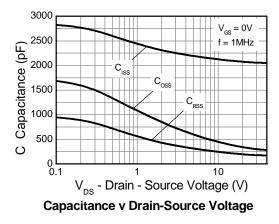


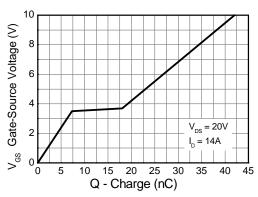
Typical Characteristics





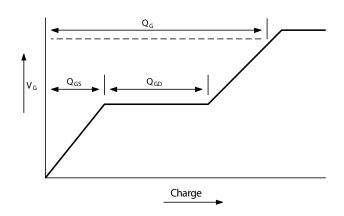
Typical Characteristics - continued





Gate-Source Voltage v Gate Charge

Test Circuits



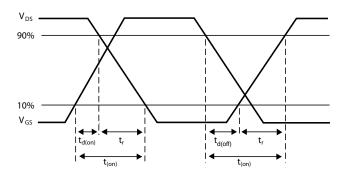
Current regulator

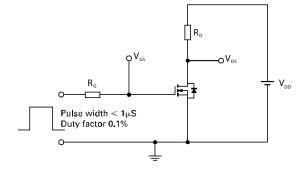
12V 0.2µF 50k D.U.T

Vos

Basic gate charge waveform

Gate charge test circuit



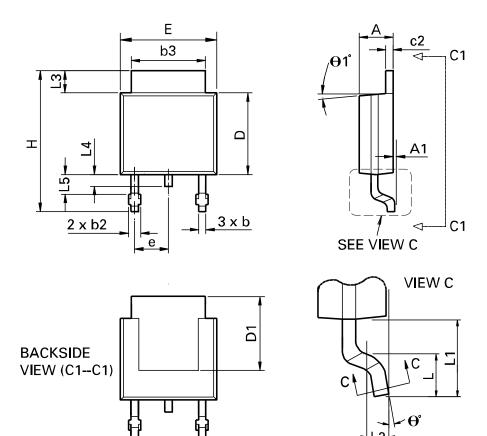


Switching time waveforms

Switching time test circuit



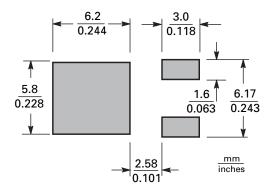
Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min Max	Min	Max		Min	Max	Min	Max	
Α	0.086	0.094	2.18	2.39	е	0.090 BSC		2.29 BSC	
A 1	-	0.005	-	0.127	Н	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
С	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	θ1°	0°	10°	0°	10°
Е	0.250	0.265	6.35	6.73	θ°	0°	15°	0°	15°
E1	0.170	_	4.32	-	-	_	-	-	-



Suggested Pad Layout



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